



# 100% Material Declaration Data Sheet PD8

PK161 (v1.3) November 12, 2013

Material Declaration Data Sheet

**Average Weight: 0.528 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.006650</b>	<b>1.26%</b>
	Silicon	7440-21-3	100.00		0.006653	
<b>Die Attach Material</b>					<b>0.001980</b>	<b>0.37%</b>
	Resin	Trade Secret	21.00		0.000415	
	Silver	7440-22-4	70.00		0.001383	
	Metal Oxide	Trade Secret	3.00		0.000059	
	Amine	Trade Secret	3.00		0.000059	
	Gamma Butyrolactone	Trade Secret	3.00		0.000059	
<b>Mold Compound</b>					<b>0.318240</b>	<b>60.31%</b>
	Resin Type Ortho Cresol Novolac	Trade Secret	13.50		0.042962	
	Silica	60676-86-0	86.50		0.275278	
<b>Leadframe</b>					<b>0.189840</b>	<b>35.98%</b>
	Copper	7440-50-8	97.50		0.185099	
	Iron	7439-89-6	2.35		0.004461	
	Phosphorus	7723-14-0	0.03		0.000057	
	Zinc	7440-66-6	0.12		0.000228	
<b>Leadframe Plating</b>					<b>0.001350</b>	<b>0.26%</b>
	Silver	7440-22-4	100.00		0.001350	
<b>Bond Wire</b>					<b>0.000410</b>	<b>0.08%</b>
	Gold	7440-57-5	100.00		0.000414	
<b>Ext. Plating</b>					<b>0.009160</b>	<b>1.74%</b>
	Tin	7440-31-5	85.00		0.007786	
	Lead	7439-92-1	15.00		0.001374	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/29/06	1.2	Updated component descriptions.
11/12/2013	1.3	New epoxy mold compound composition